ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Composition De 2005. IPC, Bannockt nd Pan-American co	claration ourn, Illinois. A opyright conver	Il rights reserved untions.	under both	This docume evel parts, th	nt is a declaration ne declaration en	n of the substanc compasses all lov	es within the n ver level mater	nanufacturer rials for whi	listed item. N ch the manufa	ote: if the iter cturer has eng	n is an assen ineering res	nbly with low consibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name* Company unique II			ique ID	ue ID Unique		Jnique ID Autho	nique ID Authority			Response Date*			
nsemi									2023-06-08				
Contact Name Title - Cont			- Contact		Phone - Contact*			1	Email - Contact*				
Product-Env-Stewards P			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Re			- Representative		I	Phone - Representative*			I	Email - Representative*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weigh	t* UC	ЭM	Unit Type
	AR0230 A0-DR1	AR0230CSSC12SUE 2 MP 1/3 CIS SO A0-DR1)		2023-06-08		MY5		257.51	mg	ŗ,	Each
Ianufacturing Proccess Info	ormation												
Terminal Plating / Grid Array Material Te		erminal Base Alloy J-STD-020 MS		J-STD-020 MSL	Rating	Peak Proces	Peak Process Body Temperatu		ure Max Time at Peak Temper		Number of Re	flow Cycles	
SnAgCu		CU Alloy 4			260 C		30		seconds	3			
omments													
or more information regarding ma	terial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl nthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	35.45	mg		Misc.	proprietary data		0.1347	mg
			Supplier	Silicon (Si)	7440-21-3		34.9643	mg
			Supplier	Aluminum (Al)	7429-90-5		0.351	mg
Die Attach	1.66	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.6225	mg
			Supplier	Ethylene Glycol	107-21-1		0.0166	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0498	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.3486	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.6225	mg
Imaging Lens	60.6	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.1894	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.1894	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.1894	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3194	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.1894	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.1894	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		44.3337	mg
Lid Attach	1.41	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.4456	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0733	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.4456	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.4456	mg
Mold Compound-Black	41.36	mg		Phenolic Resin	proprietary data		6.204	mg
			Supplier	Oxirane	39817-09-9		6.204	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.2408	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4136	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.4704	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.8272	mg
Solder Ball	38.86	mg	Supplier	Silver (Ag)	7440-22-4		1.1658	mg
			Supplier	Tin (Sn)	7440-31-5		37.4999	mg
			Supplier	Copper (Cu)	7440-50-8		0.1943	mg
ubstrate and Solder Mask	77.49	mg	В	Nickel (Ni)	7440-02-0		3.0996	mg
			Supplier	Gold (Au)	7440-57-5		0.31	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		18.5976	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		46.494	mg

			Supplier	Copper (Cu)	7440-50-8	8.9888	mg
Wire Bond - Au	0.68	mg	Supplier	Gold (Au)	7440-57-5	0.68	mg